Design a video doorbell with optimized cloud streaming and enhanced security features using SimpleLink™ Wi-Fi®

Learn how you can use the new SimpleLink™ Wi-Fi wireless microcontrollers(MCU), featuring RTP video and audio streaming over Wi-Fi with enhanced security features for your low power video doorbell design.

Reference design
- Wi-Fi Audio Streaming Reference Design
- Wi-Fi Audio Streaming Application for SimpleLink Wi-Fi CC3200 Launchpad

User Guide (reference design)
- Wi-Fi Audio Streaming Reference Design User Guide

Learn more at SimpleLink™ Wi-Fi® application tab
See additional system parts at TI video doorbell reference design page
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